

PRODUCT DATA SHEET

5RMA-RC and 5RA-RC

REACH-Compliant Liquid Fluxes

Introduction

5RMA-RC and **5RA-RC** are heat-stabilized rosin fluxes designed for soldering with preforms or wire. They are formulated for use with a wide range of temperatures and metallizations. Both fluxes are free of materials listed in the REACH SVHC list (Q2, 2015).

5RMA-RC is a no-clean, mildly activated flux. **5RA-RC** is compatible with Pb-free alloys, as well as with high-Pb and SnPb alloys.

Cleaning

5RMA-RC is a no-clean flux. Removal of post reflow flux residue is usually not necessary. If cleaning is desired, commercially available flux residue removers can be used.

Because **5RA-RC** is a fully-activated flux, the post reflow residue must be removed. Solvent-based or semi-aqueous cleaners should be used to remove any flux residues.

Packaging

Standard packaging for **5RMA-RC** and **5RA-RC** is 1 U.S. pint (0.473 liter) and 1 U.S. gallon (3.785 liters).

Storage and Handling

The shelf life of **5RMA-RC** and **5RA-RC** is 3 years when stored at 0–30°C. Flux should be allowed to reach ambient temperature prior to use. Containers should be labeled with date and time of opening.

Technical Support

Indium Corporation sets the industry standard in providing rapid response, onsite technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.

Recommended Application Notes

- *Flux and Solder Compatibility* (Form No. 97751)
- *Common Elements* (Form No. 98557)
- *Pb-Free Solder FAQs* (Form No. 97758)
- *Practical Suggestions for Preform Design* (Form No. 97763)

Other Recommended Products

- Solder preforms
- Solder wire
- Solder research kits

	5RMA-RC Flux	5RA-RC Flux
Common Surface Metallizations	Clean copper, gold, palladium, platinum, silver, solder-plate, tin	Beryllium-copper, brass, bronze, cadmium, lead, nickel, oxidized copper, rhodium
Common Alloys to Solder	AuSn, indium alloys, SnAg, Sn63, SAC, and other Pb-free alloys	AuSn, high-lead, indium alloys, SAC and other Pb-free alloys, Sn63
Application	Dipping, spray fluxing, spin coating	Spray fluxing, spin coating, dipping
Activation	Mildly activated	Fully activated
Flash Point	12°C	12°C
Flux Type Classification	ROL1	ROH1
Solid Content	27%	21%
Typical Specific Gravity	0.865	0.857
Visual Appearance	Amber liquid	Amber liquid
Water Resistivity (Ω -cm)	>100,000	<50,000
Cleaning	Not needed	Clean for high reliability

All information is for reference only.

Not to be used as incoming product specifications.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

From One Engineer To Another®

Contact our engineers: askus@indium.com

Learn more: www.indium.com



Form No. 99188 (A4) R2

ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900



©2024 Indium Corporation